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(12) United States Design Patent
Wang

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(54) **THERMAL INFRARED IMAGER**

(75) Inventor: **Hao Wang**, Hangzhou (CN)

(73) Assignee: **Hangzhou Mission Infrared Electro Optocs Technology Co., Ltd.**, Hangzhou (CN)

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

Jan. 21, 2010 (CN) 2010 3 0100468

(51) **LOC (9) Cl.** **16-06**
(52) **U.S. Cl.** **D16/132**
(58) **Field of Classification Search** D16/130, D16/132, 133, 206, 200, 201, 203; 359/630; D10/46, 66, 50, 70; 33/290, 291, 292, 285
See application file for complete search history.

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Primary Examiner — Paula Greene
(74) *Attorney, Agent, or Firm* — Jacobson Holman PLLC; Jiwen Chen

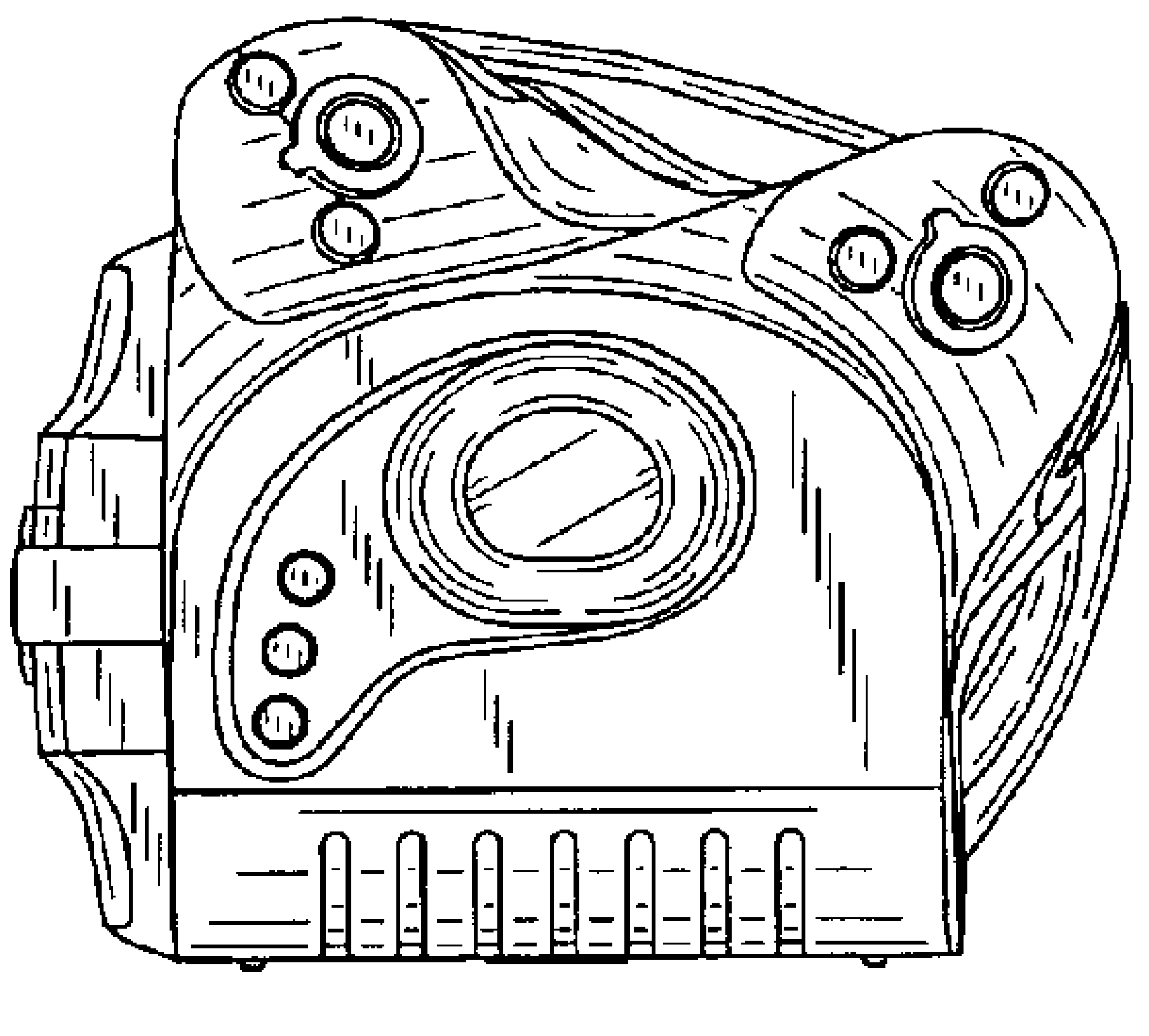
(57) CLAIM

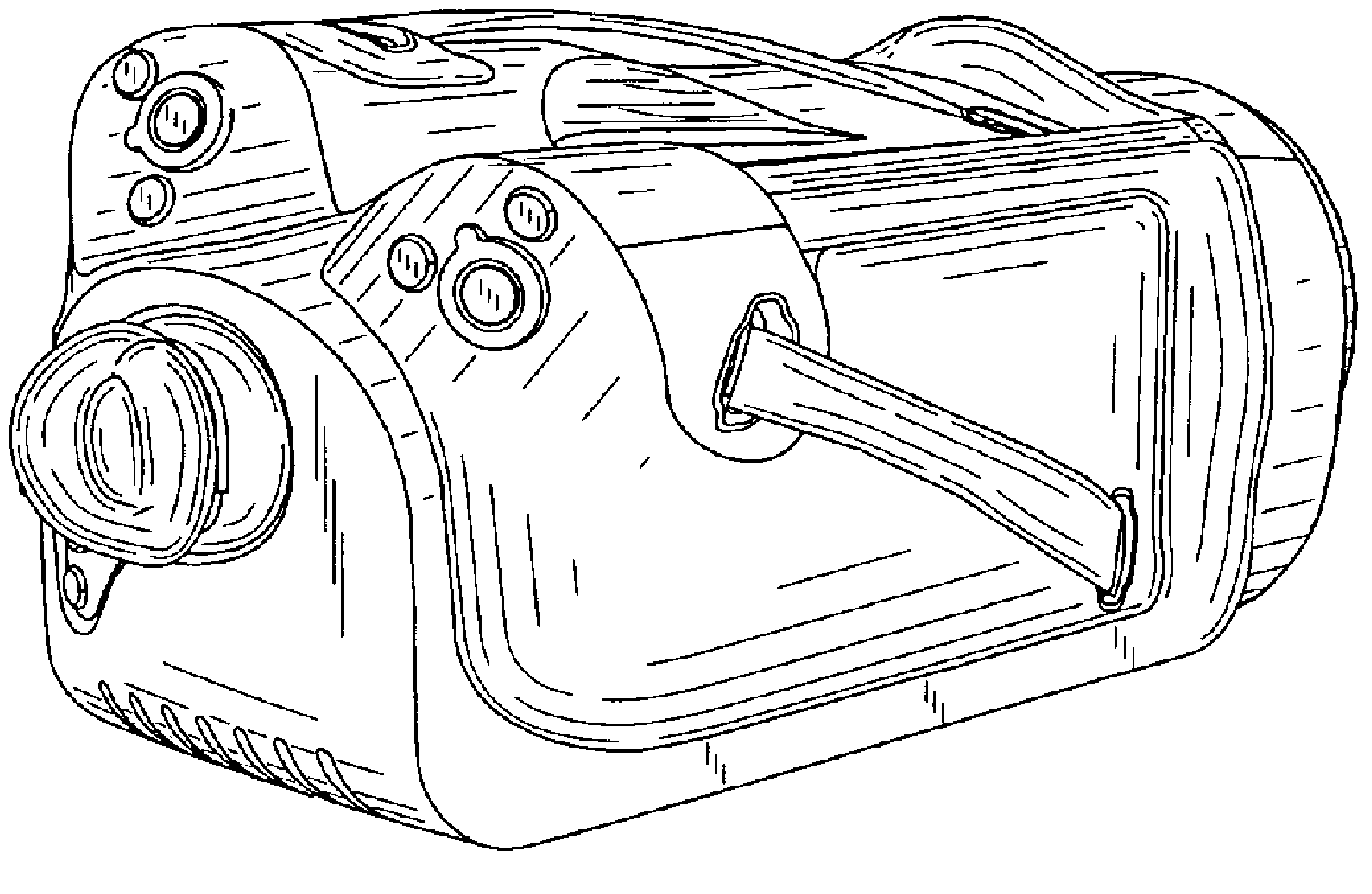
I claim the ornamental design for the thermal infrared imager, as shown and described.

DESCRIPTION

FIG. **1** is a front elevational view of the thermal infrared imager when it is in a closed position;
FIG. **2** is a rear elevational view of the thermal infrared imager when it is in a closed position;
FIG. **3** is a bottom plan view of the thermal infrared imager when it is in a closed position;
FIG. **4** is a top plan view of the thermal infrared imager when it is in a closed position;
FIG. **5** is a left side view of the thermal infrared imager when it is in a closed position;
FIG. **6** is a right side view of the thermal infrared imager when it is in a closed position;
FIG. **7** is a rear perspective view of the thermal infrared imager when it is in a closed position;
FIG. **8** is a right side view of the thermal infrared imager when it is in an open position;
FIG. **9** is a front elevational view of the thermal infrared imager when it is in an open position;
FIG. **10** is a rear elevational view of the thermal infrared imager when it is in an open position;
FIG. **11** is a top plan view of the thermal infrared imager when it is in an open position; and,
FIG. **12** is a bottom plan view of the thermal infrared imager when it is in an open position.
The broken lines form no part of the claimed design.

1 Claim, 6 Drawing Sheets





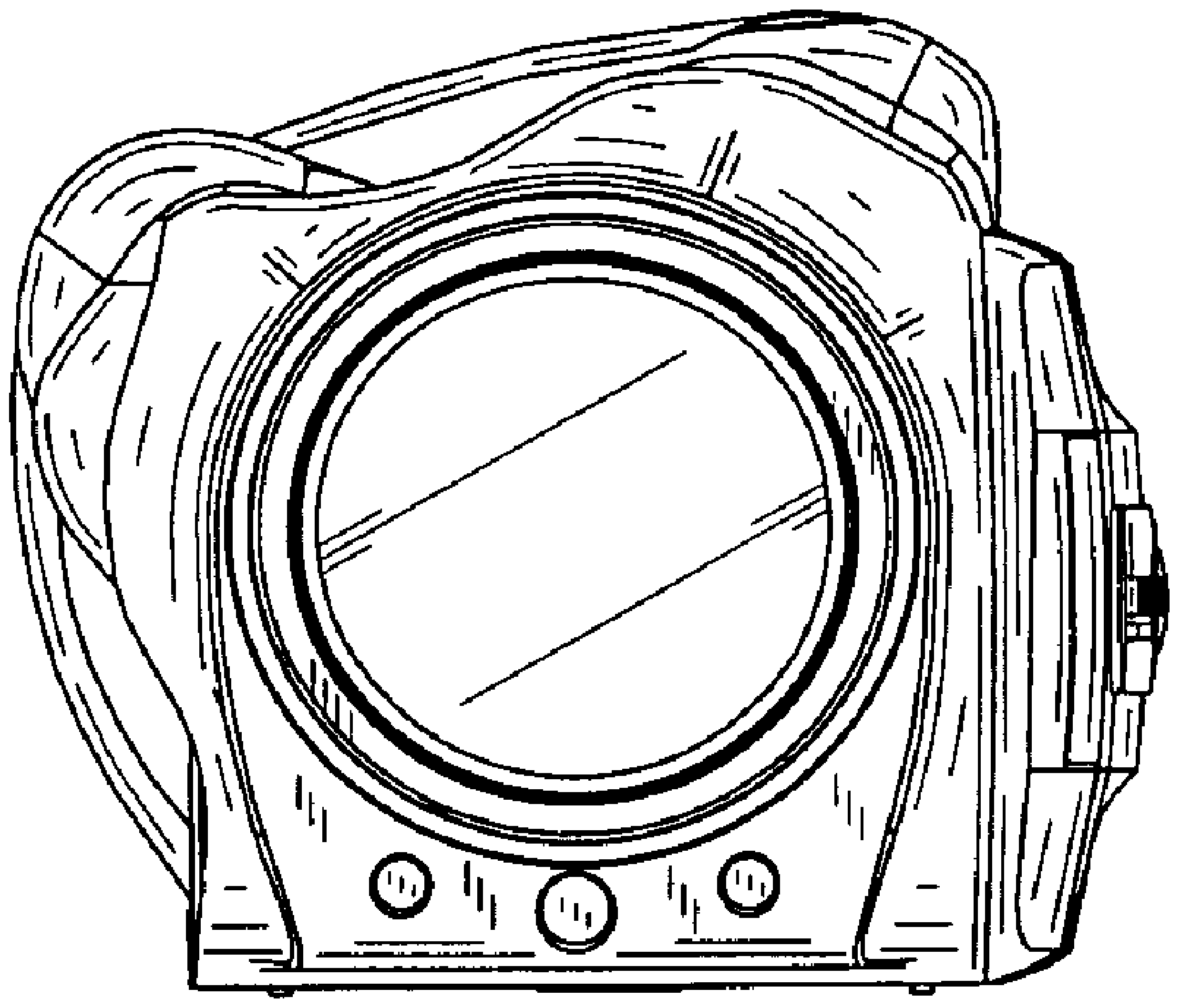


Fig. 1

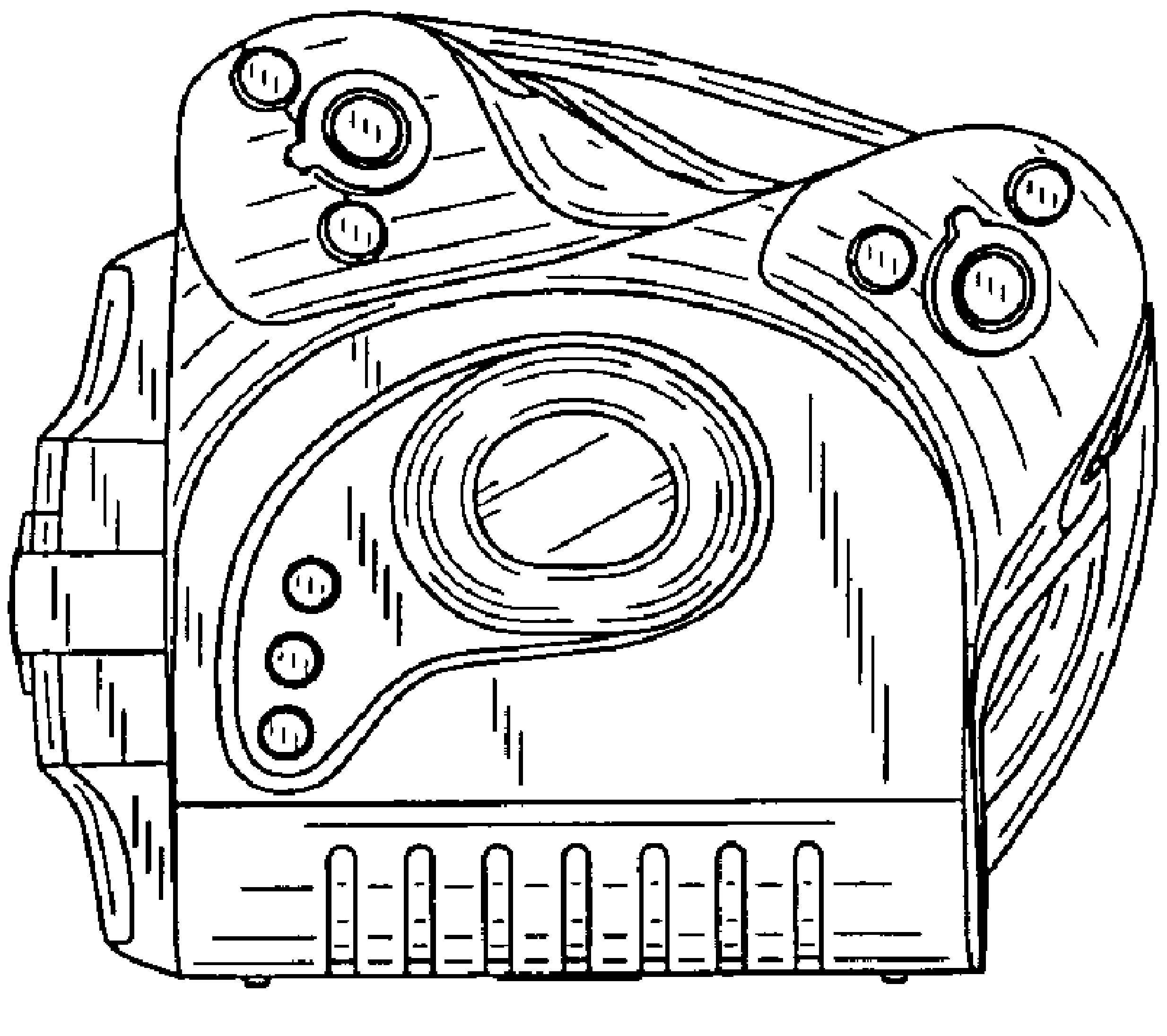


Fig. 2

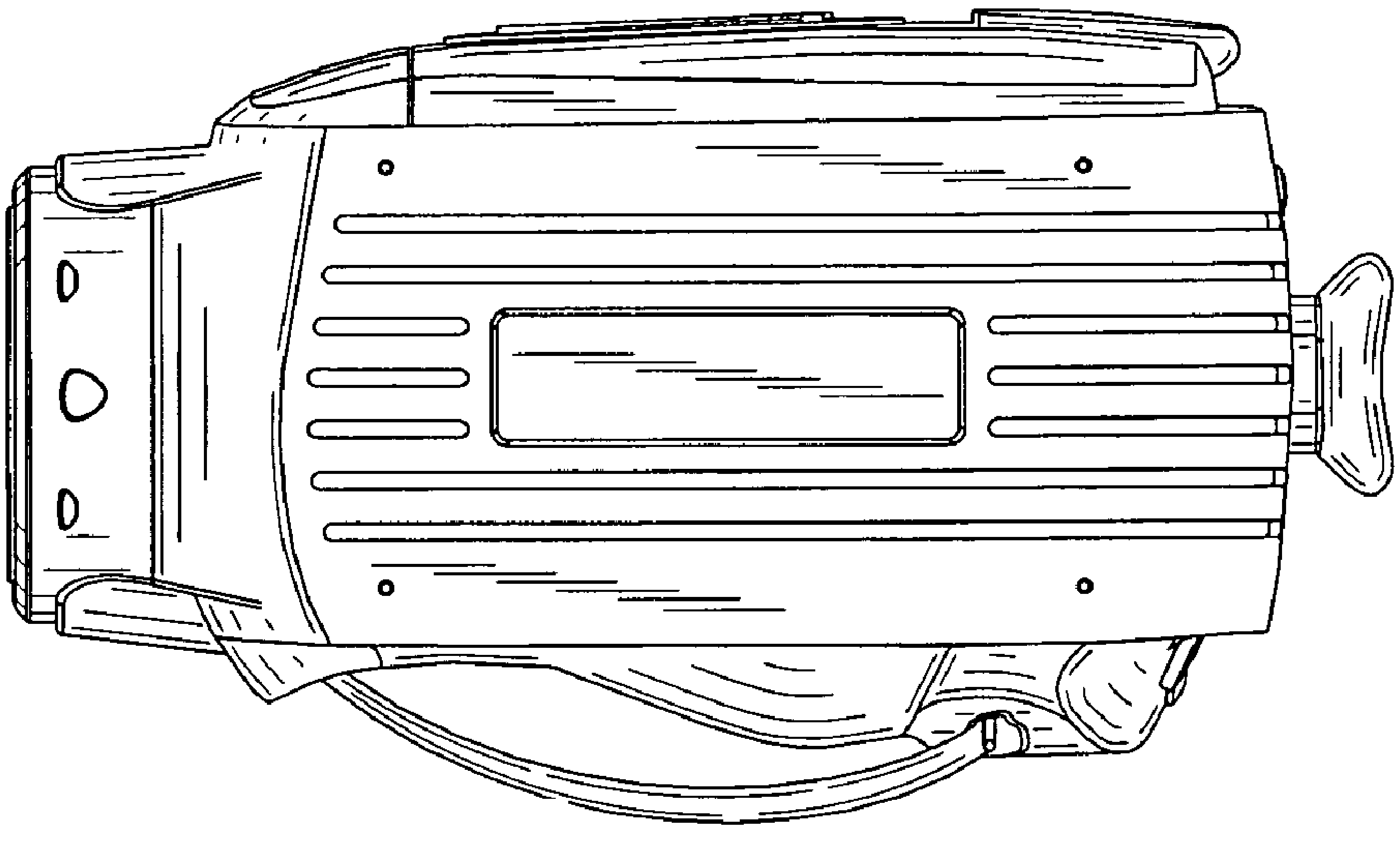
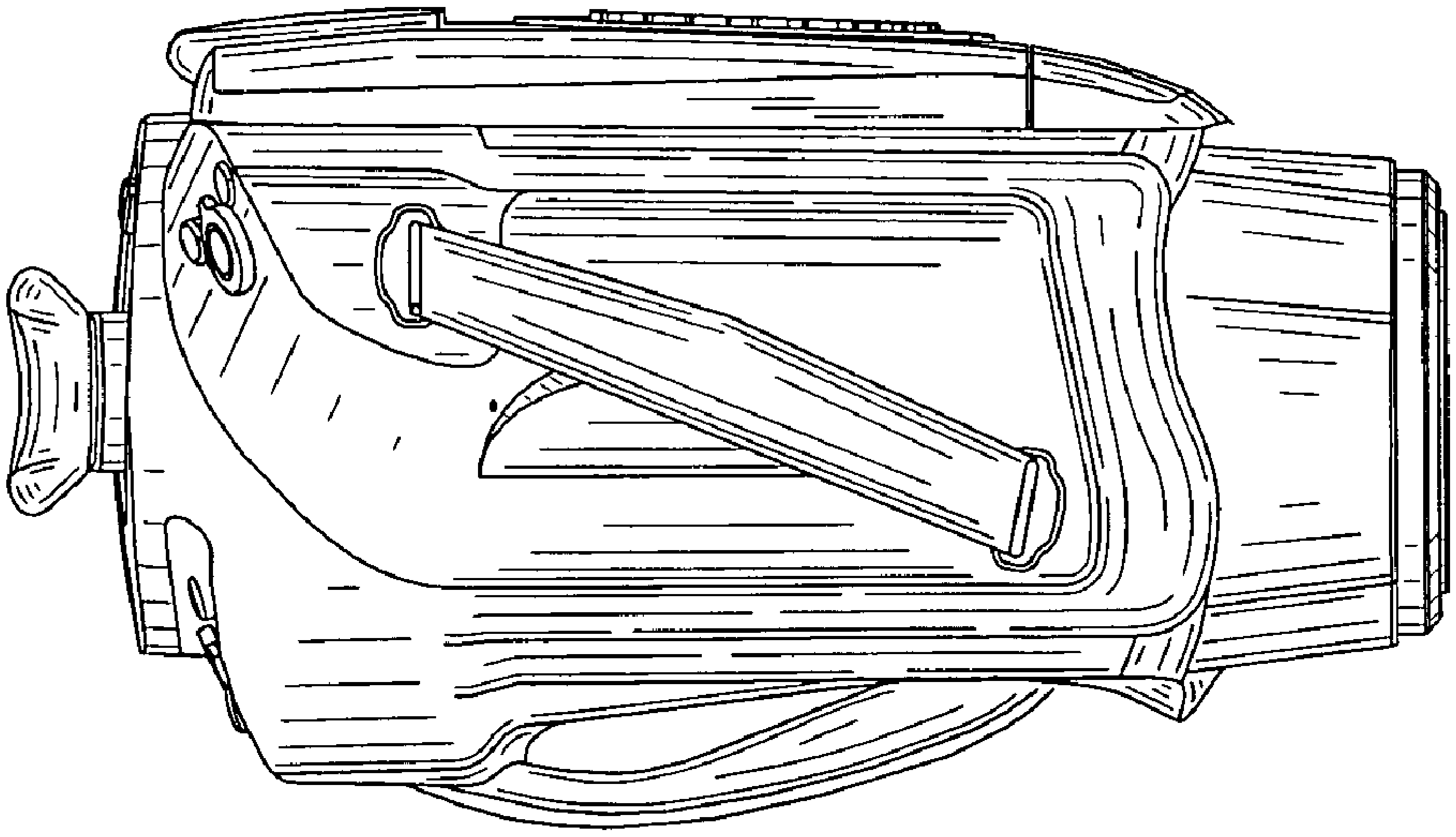


Fig. 3



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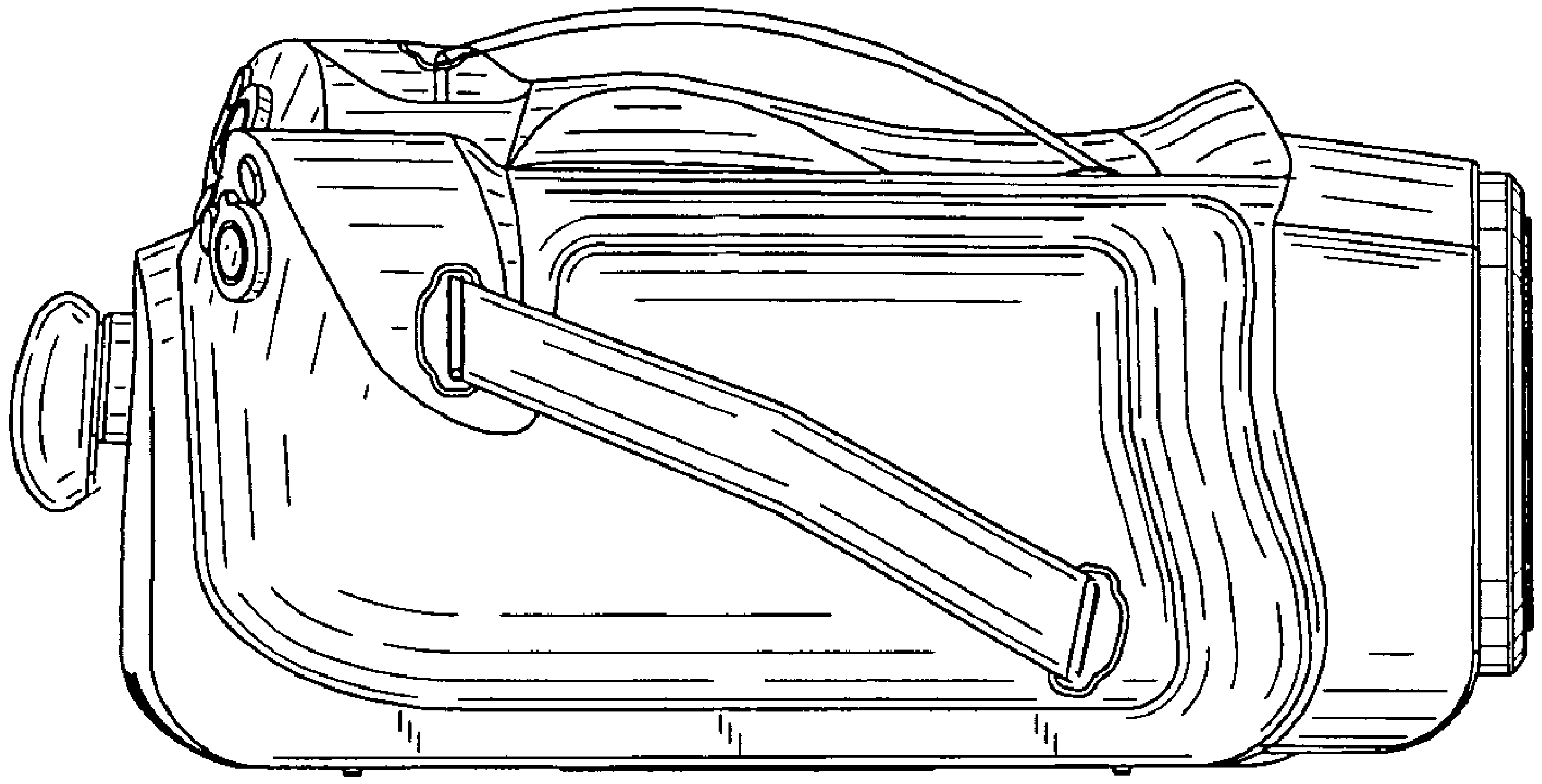

Fig. 5

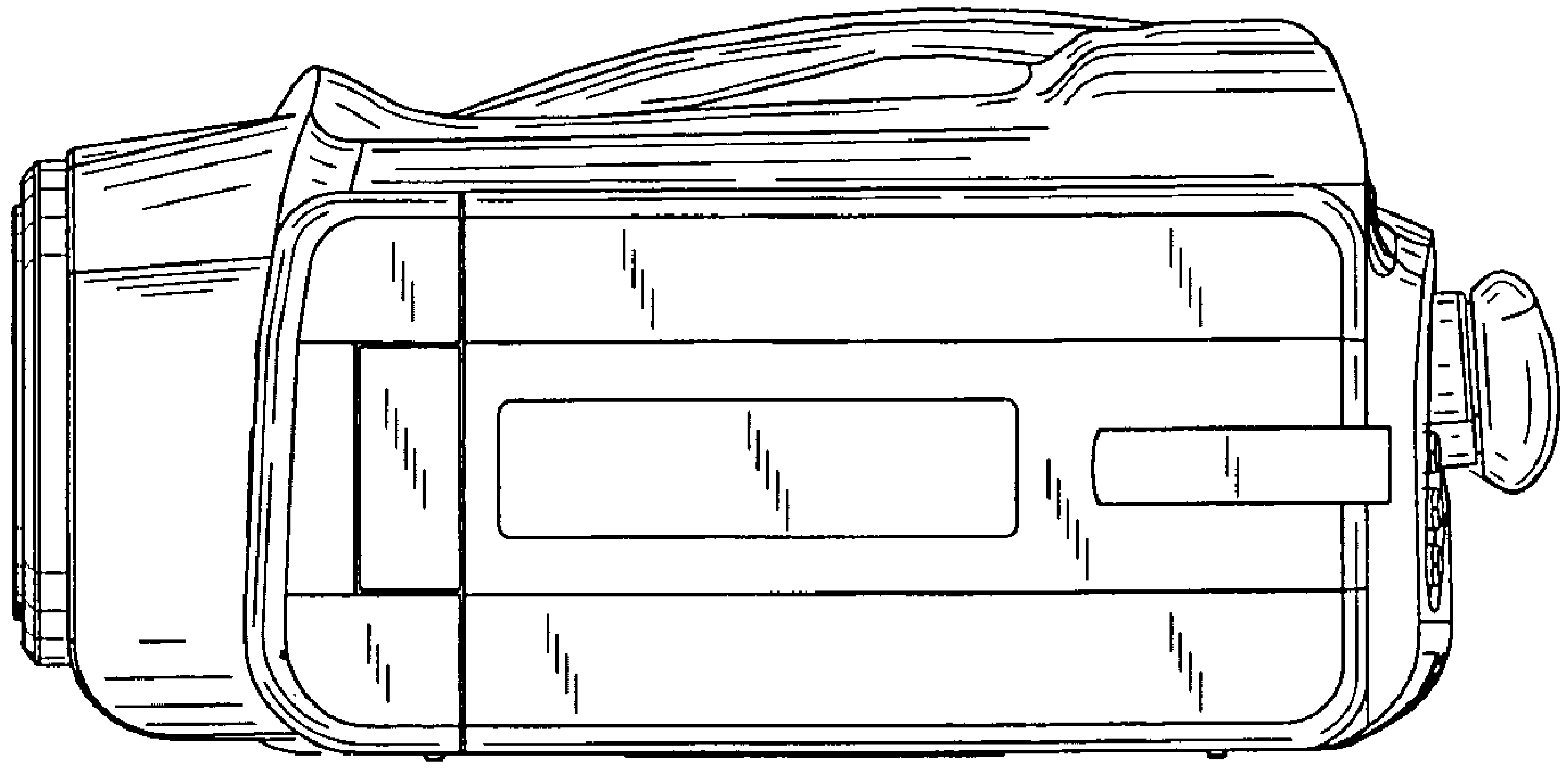

Fig. 6

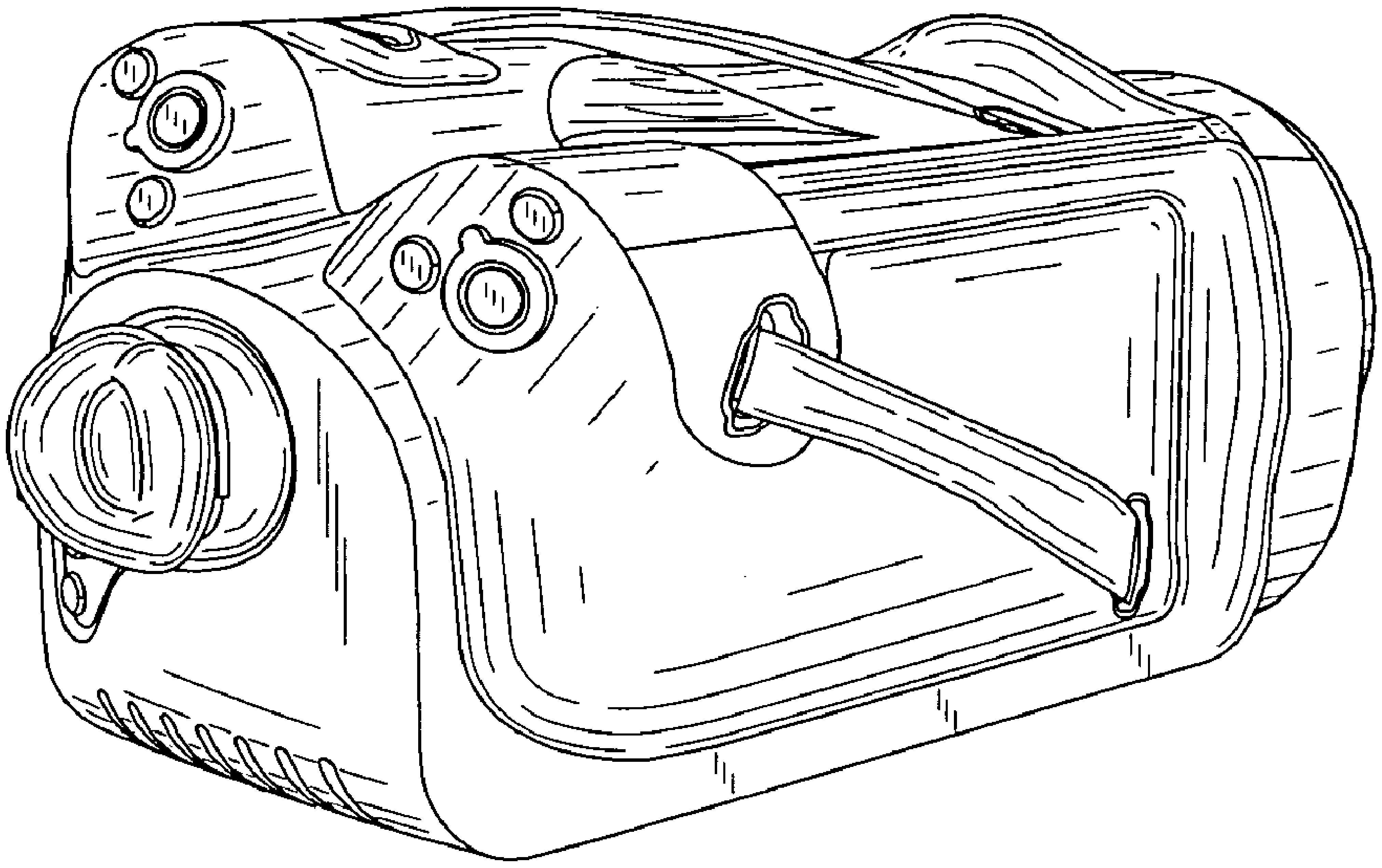

Fig. 7

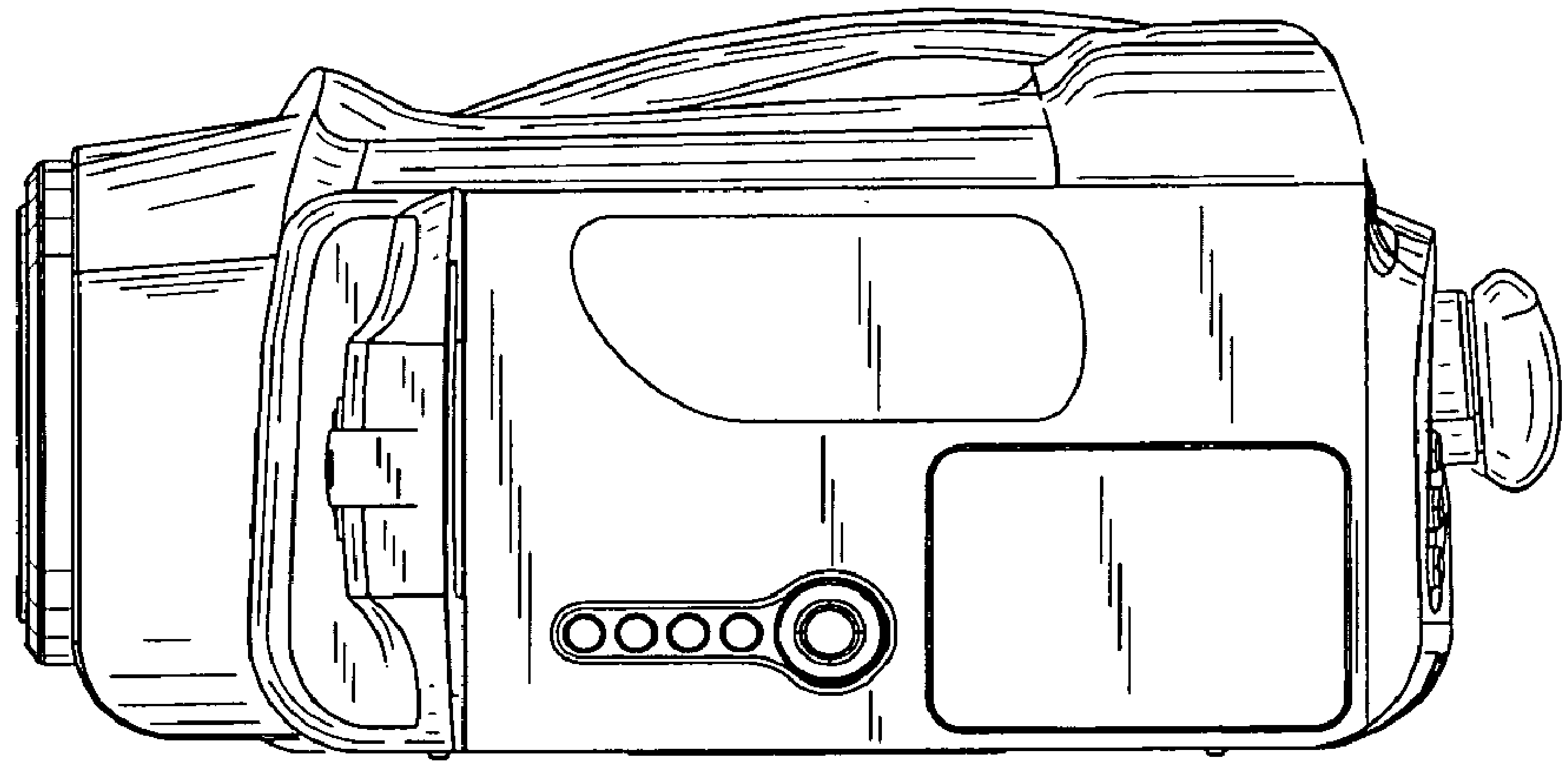

Fig. 8

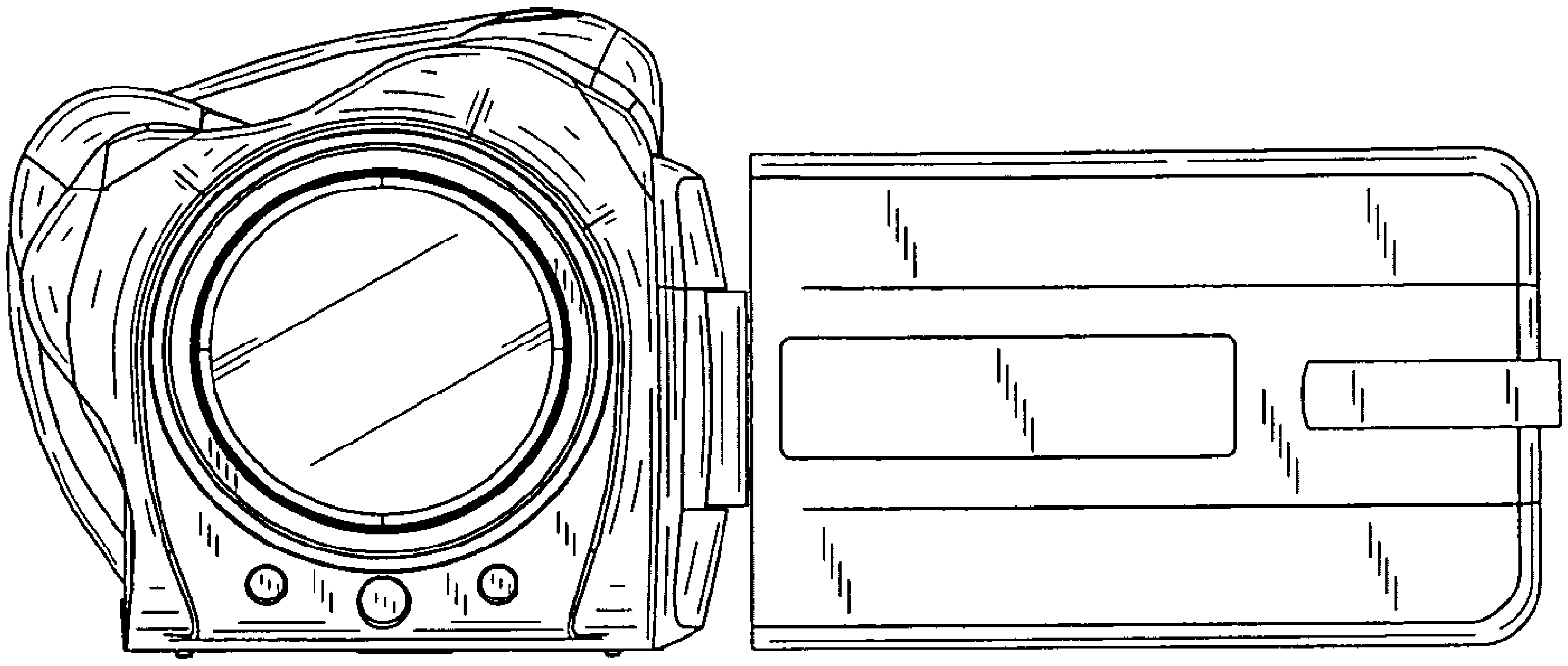

Fig. 9

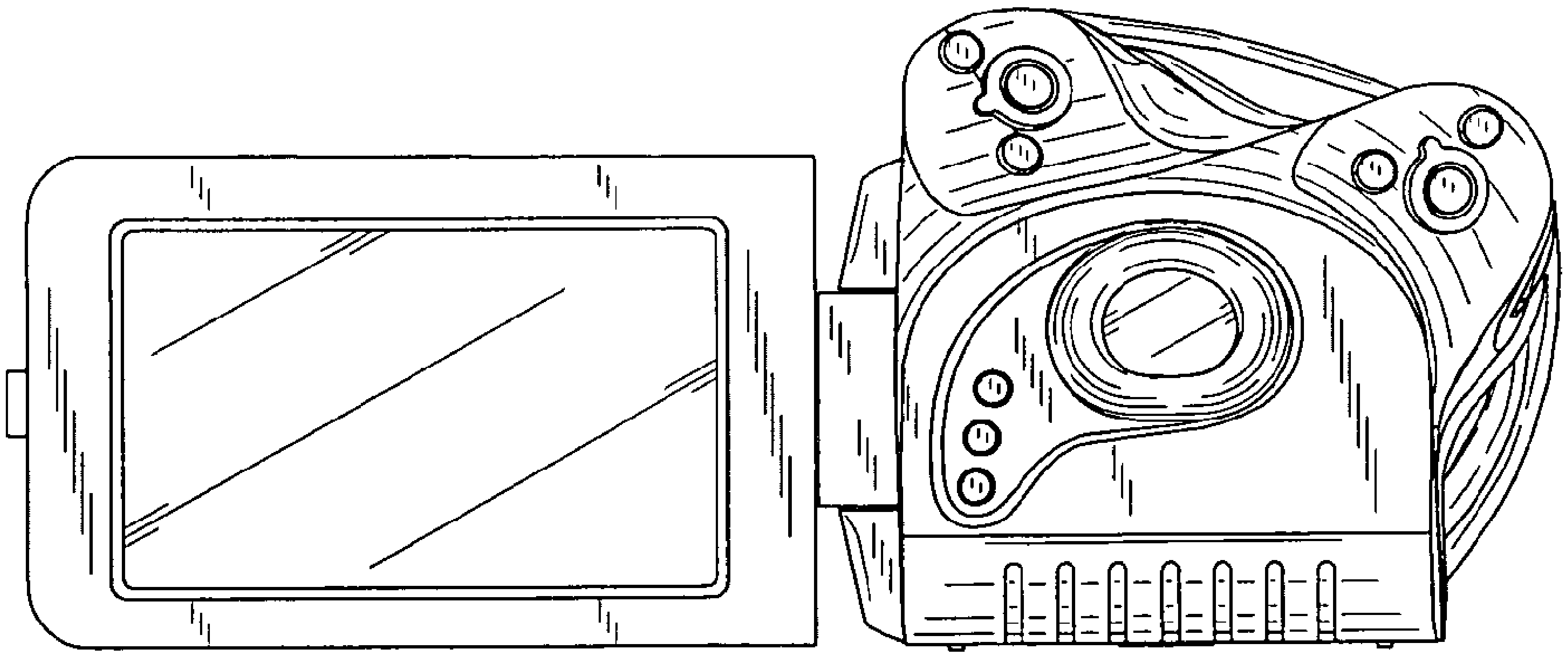

Fig. 10

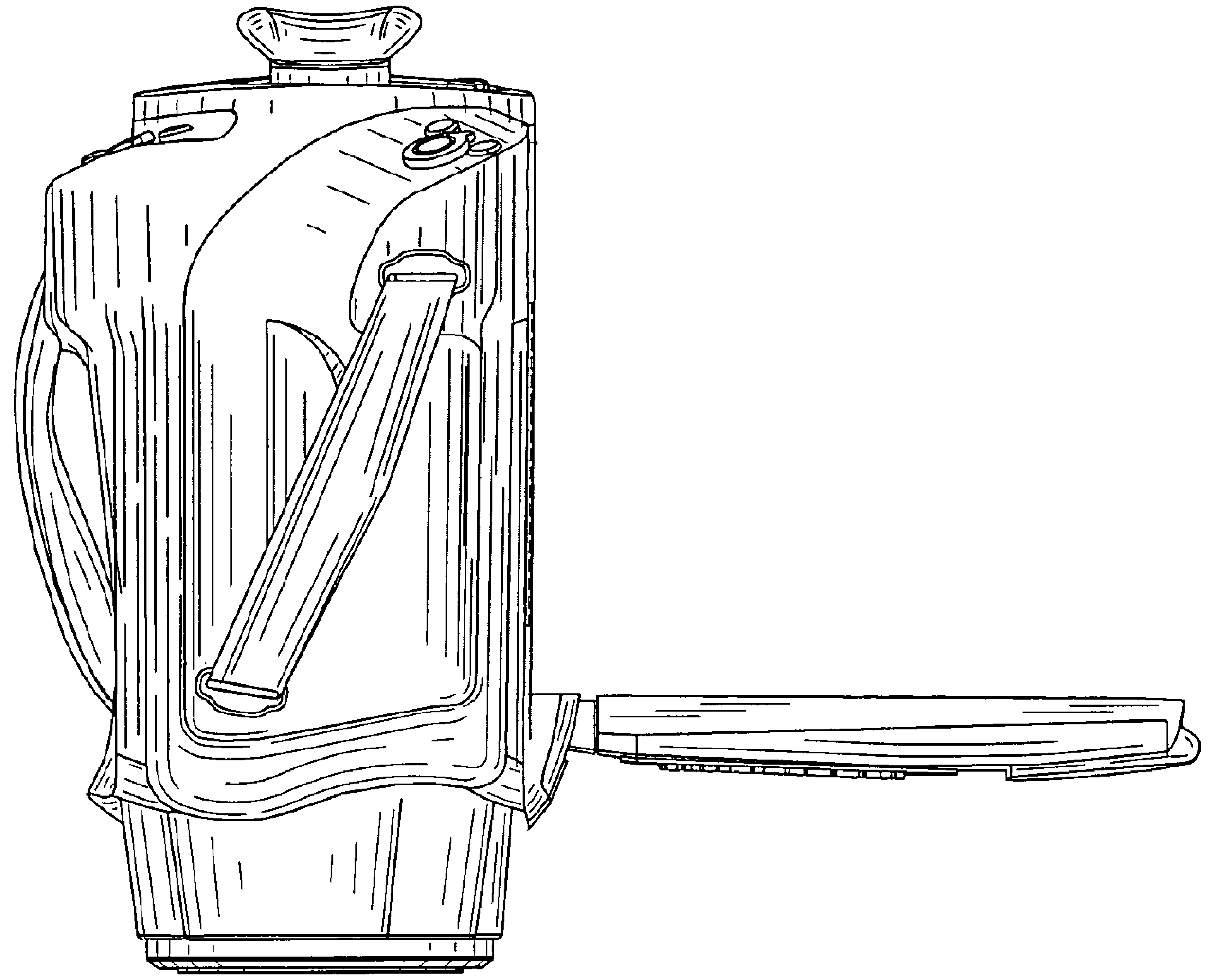

Fig. 11

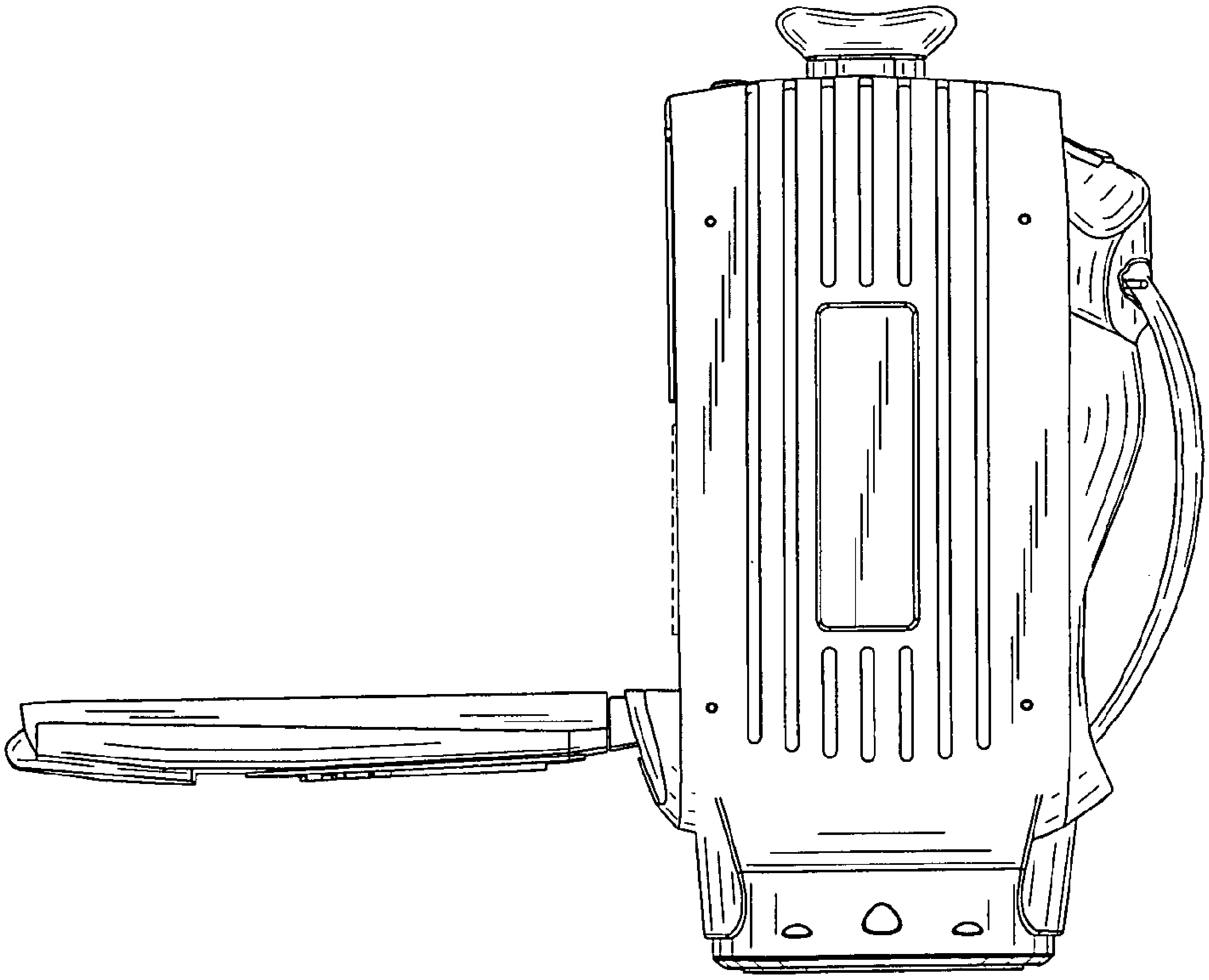

Fig. 12